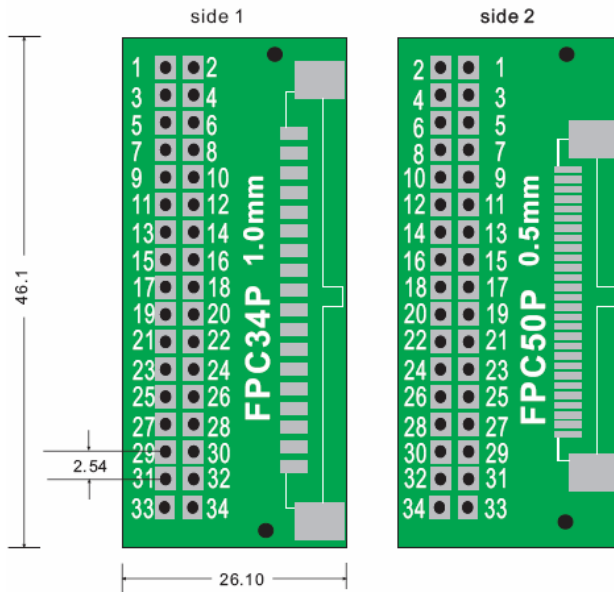


SMD package to DIP Converter Board

Version 02/15

Item no. 1274826



Function:
FPC34P & FPC50P package to DIP

Technical Data:

Board Material	FR-4
SMD package	FPC34P (side 1) FPC50P (side 2)
Board Thickness	1.6mm ± 0.1mm
Surface Technioque	Spray tin 5-8um
Copper Thickness	35um ± 5um
Solderability	260°C at 3s - 1.1%
Flammability	V-0
Surface Resistivity	1.0 x 10 ⁶ MΩ
Volume Resistivity	1.0 x 10 ⁸ MΩ - cm
Arc Resistance	125sec.

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